



# Product Change Notification

**Change Notification #:** 115667 - 01  
**Change Title:** Intel® X-GOLD™ 213,  
PCN 115667-01, Product Discontinuance,  
End of Life  
[Reason for Revision: Publish to Public QDMS](#)  
**Date of Publication:** July 14, 2017

## Key Characteristics of the Change:

Product Discontinuance

## Forecasted Key Milestones:

Last Product Discontinuance Order Date:	July 10, 2017
Last Product Discontinuance Shipment Date:	July 10, 2017

[Reason for Revision: Publish to Public QDMS](#)

## Description of Change to the Customer:

The Intel® X-GOLD™ 213 product listed on the "Products Affected/Intel Ordering Codes" table below will be discontinued and unavailable for additional orders after the "Last Product Discontinuance Order Date" (see "Key Milestones" above).

## Customer Impact of Change and Recommended Action:

This notification is for recordkeeping only, the product is no longer available. See your local Intel Sales Representative for alternative products

## Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	S-Spec	MM#
Intel® X-GOLD™ 213	PMB8810N.V2	S LHMB	913627
Intel® X-GOLD™ 213	PMB8810N.V2	S LHM9	913646
Intel® X-GOLD™ 213	PMB8810N.V2	S LHM8	913647
Intel® X-GOLD™ 213	PMB8810N.V2	S LHK8	913822
Intel® X-GOLD™ 213	PMB8810N.V2	S LHNH	914020
Intel® X-GOLD™ 213	PMB8810N.V2	S LHNE	914023
Intel® X-GOLD™ 213	PMB8810N.V2	S LHHR	914169
Intel® X-GOLD™ 213	PMB8810N.V2	S LHHQ	914170
Intel® X-GOLD™ 213	PMB8810N.V2	S LHHL	914174
Intel® X-GOLD™ 213	PMB8810N.V2	S LHHK	914175
Intel® X-GOLD™ 213	PMB8810N.V2	S LHHJ	914176
Intel® X-GOLD™ 213	PMB8810N.V2	S LJ6X	915366
Intel® X-GOLD™ 213	PMB8810N.V2	S LJND	920316

## PCN Revision History:

**Date of Revision:**

July 10, 2017

July 14, 2017

**Revision Number:**

00

01

**Reason:**

Originally Published PCN

Publish to Public QDMS



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## 115667 - 01

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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